


NOTES

- MATERIALS:**
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
- FINISH:**
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
- PACKAGE CONFORMS TO JEDEC MO-220**

PROPRIETARY AND CONFIDENTIAL
THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF QPTECHNOLOGIES. ANY REPRODUCTION, IN PART, OR AS A WHOLE WITHOUT THE WRITTEN PERMISSION OF QPTECHNOLOGIES IS PROHIBITED.

		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		NAME	DATE	 QPTECHNOLOGIES <small>A DIVISION OF PROMEX INDUSTRIES QPTECHNOLOGIES.COM</small>			
				DRAWN	D. Abbe 8/1/11				
				CHECKED	S. Swen 8/1/11				
				ENG APPR.	S. Swen 8/1/11	TITLE: QP-QFN16-5MM-0.80MM			
				COMMENTS:					
		MATERIAL	SEE NOTE 1			SIZE B	DWG. NO. 500380	REV A	
NEXT ASSY	USED ON	FINISH	SEE NOTE 2			SCALE: 10:1		WEIGHT:	SHEET 1 OF 1
APPLICATION		DO NOT SCALE DRAWING							

